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FFSP1265A

Silicon Carbide Schottky Diode

650 V, 12 A

Features

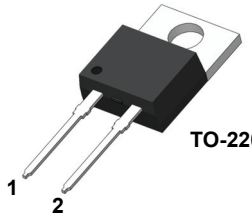
- Max Junction Temperature 175 °C
- Avalanche Rated 72 mJ
- High Surge Current Capacity
- Positive Temperature Coefficient
- Ease of Paralleling
- No Reverse Recovery / No Forward Recovery

Applications

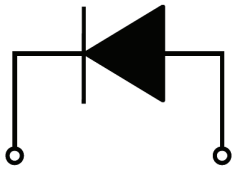
- General Purpose
- SMPS, Solar Inverter, UPS
- Power Switching Circuits

Description

Silicon Carbide (SiC) Schottky Diodes use a completely new technology that provides superior switching performance and higher reliability compared to Silicon. No reverse recovery current, temperature independent switching characteristics, and excellent thermal performance sets Silicon Carbide as the next generation of power semiconductor. System benefits include highest efficiency, faster operating frequency, increased power density, reduced EMI, and reduced system size and cost.



1. Cathode 2. Anode



1. Cathode 2. Anode

Absolute Maximum Ratings T_C = 25 °C unless otherwise noted.

Symbol	Parameter		FFSP1265A	Unit
V_{RRM}	Peak Repetitive Reverse Voltage		650	V
E_{AS}	Single Pulse Avalanche Energy (Note 1)		72	mJ
I_F	Continuous Rectified Forward Current @ T_C < 147°C		12	A
	Continuous Rectified Forward Current @ T_C < 135°C		15	A
$I_{F, Max}$	Non-Repetitive Peak Forward Surge Current	T_C = 25 °C, 10 μs	940	A
		T_C = 150 °C, 10 μs	890	A
$I_{F,SM}$	Non-Repetitive Forward Surge Current	Half-Sine Pulse, t_p = 8.3 ms	70	A
$I_{F,RM}$	Repetitive Forward Surge Current	Half-Sine Pulse, t_p = 8.3 ms	43	A
Ptot	Power Dissipation	T_C = 25 °C	115	W
		T_C = 150 °C	19	W
T_J, T_{STG}	Operating and Storage Temperature Range		-55 to +175	°C

Thermal Characteristic

Symbol	Parameter	Rating	Unit
$R_{\theta JC}$	Thermal Resistance, Junction to Case, Max	1.3	°C/W

Semiconductor Components Industries, LLC, 2017
Sep, 2017, Rev.1.0

Publication Order Number:
FFSP1265A/D

Package Marking and Ordering Information

Part Number	Top Mark	Package	Packing Method	Reel Size	Tape Width	Quantity
FFSP1265A	FFSP1265A	TO-220-2L	Tube	N/A	N/A	50 units

Electrical Characteristics T_C = 25 °C unless otherwise noted.

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
V_F	Forward Voltage	I_F = 12 A, T_C = 25 °C	-	1.5	1.75	V
		I_F = 12 A, T_C = 125 °C	-	1.6	2	
		I_F = 12 A, T_C = 175 °C	-	1.72	2.4	
I_R	Reverse Current	V_R = 650 V, T_C = 25 °C	-	-	200	μA
		V_R = 650 V, T_C = 125 °C	-	-	400	
		V_R = 650 V, T_C = 175 °C	-	-	600	
Q_C	Total Capacitive Charge	V = 400 V	-	40	-	nC
C	Total Capacitance	V_R = 1 V, f = 100 kHz	-	665	-	pF
		V_R = 200 V, f = 100 kHz	-	74	-	
		V_R = 400 V, f = 100 kHz	-	54	-	

Notes:
1: EAS of 72 mJ is based on starting T_J = 25 °C, L = 0.5 mH, I_{AS} = 17A, V = 50 V.

Typical Characteristics T_J = 25 °C unless otherwise noted.

Figure 1. Forward Characteristics

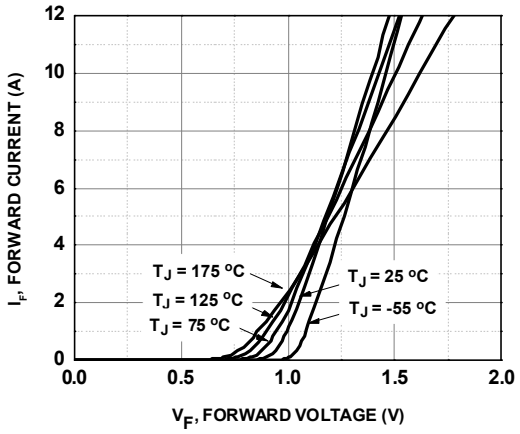


Figure 2. Reverse Characteristics

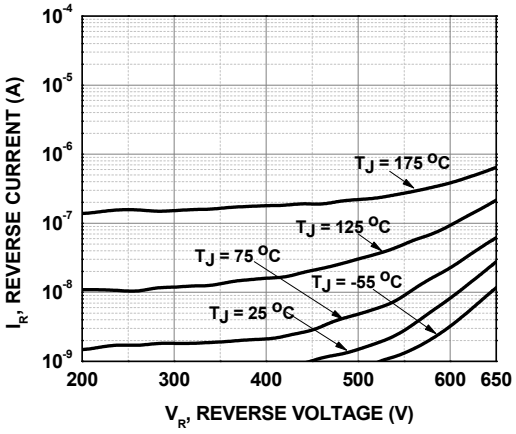


Figure 3. Current Derating

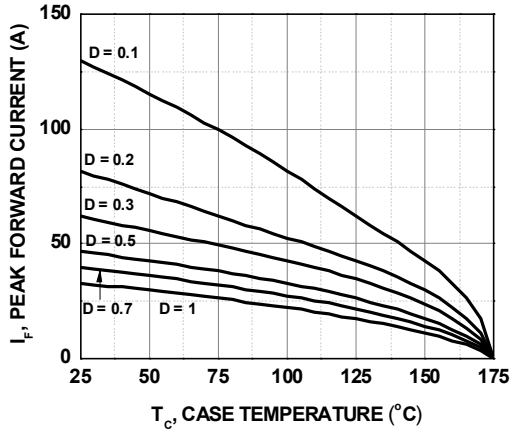
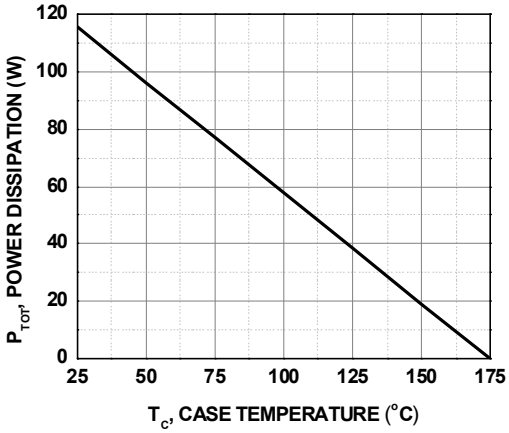


Figure 4. Power Derating



Typical Characteristics T_J = 25 °C unless otherwise noted.

Figure 5. Capacitive Charge vs. Reverse Voltage

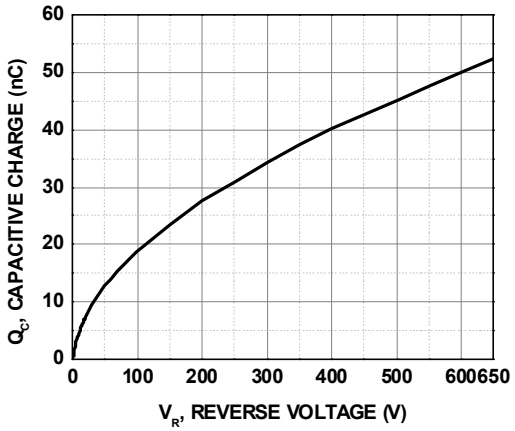


Figure 6. Capacitance vs. Reverse Voltage

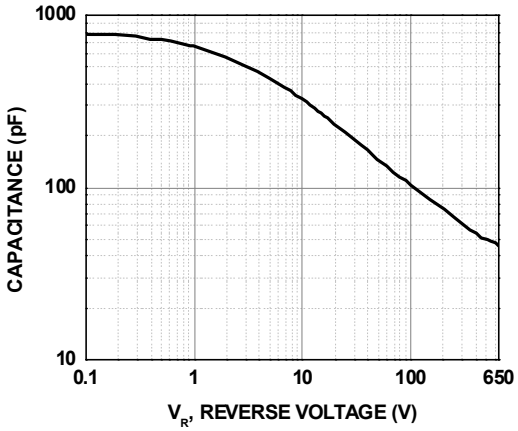


Figure 7. Capacitance Stored Energy

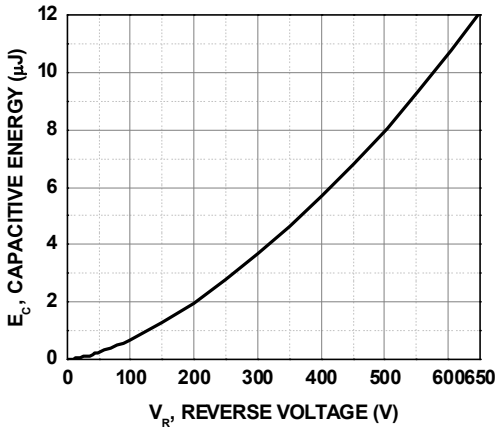
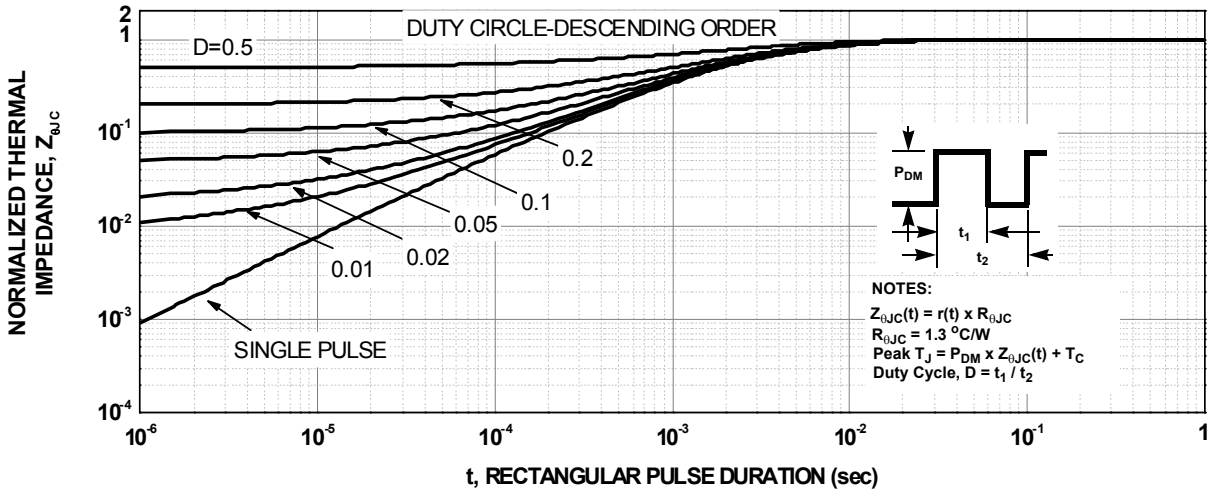
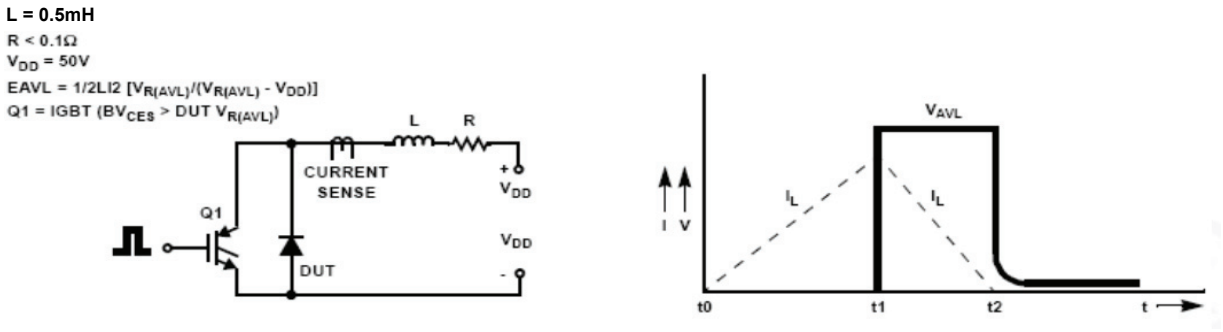


Figure 8. Junction-to-Case Transient Thermal Response Curve

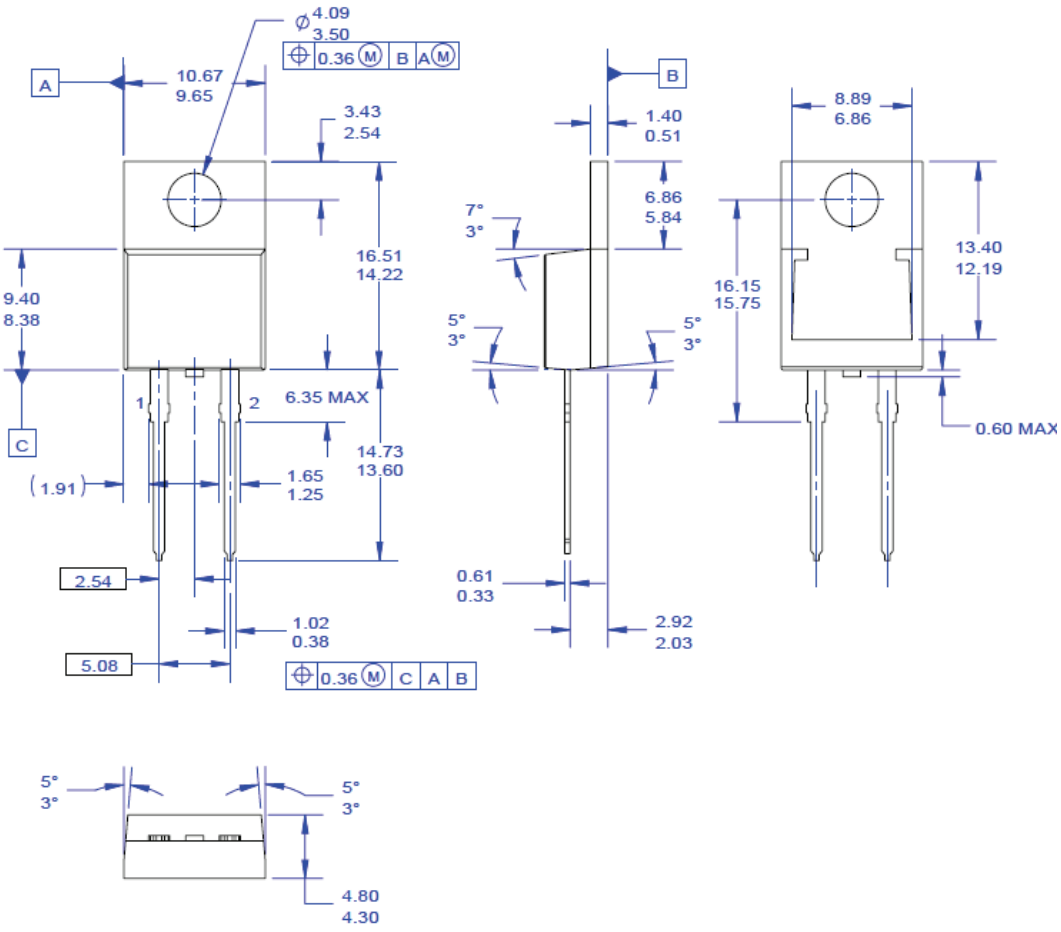


Test Circuit and Waveforms

Figure 9. Unclamped Inductive Switching Test Circuit & Waveform



Mechanical Dimensions



NOTES:

A. PACKAGE REFERENCE: JEDEC TO220,ISSUE K, VARIATION AC,DATED APRIL 2002.
B. ALL DIMENSIONS ARE IN MILLIMETERS.
C. DIMENSION AND TOLERANCE AS PER ASME Y14.5-2009.
D. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH AND TIE BAR PROTRUSIONS.
E. DRAWING FILE NAME: TO220A02REV5

Figure10. TO-220 2L - TO-220, MOLDED, 2LD